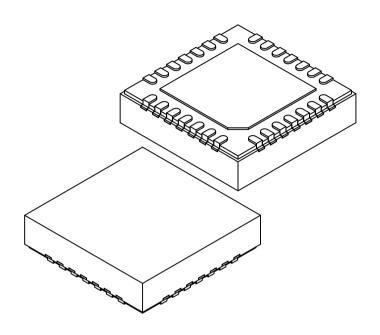
## 28-Lead Very Thin Plastic Quad Flat, No Lead Package (3LW) – 4x4x1.0 mm Body [VQFN] With 2.65 mm Exposed Pad and Stepped Wettable Flanks

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	28		
Pitch	е	0.40 BSC		
Overall Height	Α	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.203 REF		
Overall Length	D	4.00 BSC		
Exposed Pad Length	D2	2.55	2.65	2.75
Overall Width	Е	4.00 BSC		
Exposed Pad Width	E2	2.55	2.65	2.75
Exposed Pad Index Chamfer	CH	0.35 REF		
Terminal Width	b	0.15	0.20	0.25
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.275 REF		
Wettable Flank Step Cut Length	D3	_	_	0.085
Wettable Flank Step Cut Height	A4	0.10	_	0.19

## Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.